

**LTM4618 BGA-PBF-84LD 15mm X 9mm X 4.92mm (TABLE OF MATERIAL DECLARATION)**

*The package is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1411	Barium Compounds	7727-43-7	0.0023	1.63
				Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline)	13776-74-4, 7631-86-9	0.0485	30.99
				Copper Metal	7440-50-8	0.0511	36.25
				Copper Compounds	1328-53-6	0.0000	0.01
				Ecotoxic substances	7440-38-2, 7440-28-0	0.0000	0.00
				Gold metal or alloy	7440-57-5	0.0008	0.55
				Nickel	7440-02-0	0.0036	2.54
				Zinc	7440-66-6	0.0000	0.03
				Continuous Filament Fiber Glass	65997-17-3	0.0344	24.35
				Chromium(III) Oxide	1308-38-9	0.0000	0.00
				Silica amorphous	7631-86-9	0.0000	0.02
				Talc:not containing fibers like asbestors	14807-96-6	0.0003	0.19
2	Solder Paste	Alloy	0.0237	Cyanoguanidine	461-58-5	0.0000	0.01
				Sn	7440-31-5	0.0226	95.00
3	Passive/Active Components		0.7268	Sb	7440-36-0	0.0012	5.00
				Iron Powder (Fe)	7439-89-6	0.4247	58.44
4	Active Ics	Silicon	0.0032	Copper (Cu)	7440-50-8	0.2545	35.01
				Nickel (Ni)	7440-02-0	0.0071	0.97
				Tin (Sn)	7440-31-5	0.0025	0.35
				Ceramic (Ba compounds)	12047-27-7	0.0380	5.23
				Silicon	7440-21-3	0.0032	100.00
5	Wire	Gold	0.0006	Au	7440-57-5	0.0006	99.99
2	Solder Ball	Alloy	0.1596	Tin (Sn)	7440-31-5	0.1540	96.50
				Silver (Ag)	7440-22-4	0.0048	3.00
				Copper (Cu)	7440-50-8	0.0008	0.50
6	Encapsulation	Epoxy Resin	0.8174	Fused Silica	60676-86-0	0.6310	77.20
				Epoxy Resin	non-disclosure	0.0727	8.90
				Phenol Resin	non-disclosure	0.0727	8.90
				Crytalline Silica	14808-60-7	0.0245	3.00
				Carbon Black	1333-86-4	0.0041	0.50
				Metal Hydroxide	non-disclosure	0.0123	1.50
Total Package Weight			1.8724				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts